

December 1983 Revised February 1999

MM74HCT08 Quad 2-Input AND Gate

General Description

The MM74HCT08 is a logic function fabricated by using advanced silicon-gate CMOS technology which provides the inherent benefits of CMOS—low quiescent power and wide power supply range. This device is input and output characteristic and pinout compatible with standard 74LS logic families. All inputs are protected from static discharge damage by internal diodes to $\rm V_{CC}$ and ground.

MM74HCT devices are intended to interface between TTL and NMOS components and standard CMOS devices.

These parts are also plug-in replacements for LS-TTL devices and can be used to reduce power consumption in existing designs.

Features

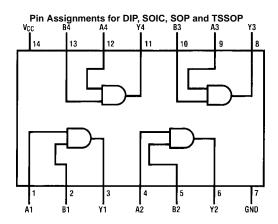
- TTL, LS pin-out and threshold compatible
- Fast switching: t_{PLH}, t_{PHL} = 12 ns (typ)
- Low power: 10 µW at DC
- High fan-out, 10 LS-TTL loads

Ordering Code:

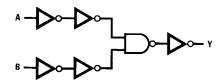
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Order Number	Package Number	Package Description			
MM74HCT08M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow			
MM74HCT08SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide			
MM74HCT08MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide			
MM74HCT08N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide			

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram



Logic Diagram



Absolute Maximum Ratings(Note 1)

(Note 2)

DC V_{CC} or GND Current, per pin (I_{CC}) ± 50 mA Storage Temperature Range (T_{STG}) -65°C to $+150^{\circ}\text{C}$

Power Dissipation (P_D)

(Note 3) 600 mW S.O. Package only 500 mW

Lead Temperature (T_L)

(Soldering 10 seconds) 260°C

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V _{CC})	4.5	5.5	V
DC Input or Output Voltage			
(V _{IN} , V _{OUT})	0	V_{CC}	V
Operating Temperature Range (T _A)	-40	+85	°C
Input Rise or Fall Times			
(t ₋ t ₄)		500	ns

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package –12

mW/°C from 65°C to 85°C.

DC Electrical Characteristics

 $V_{CC} = 5V \pm 10\%$ (unless otherwise specified)

Symbol	Parameter	Conditions	T _A = 25°C		$T_A = -40 \text{ to } 85^{\circ}\text{C}$	T _A = -55 to 125°C	Units
Зупівої		Conditions	Тур	Guaranteed Limits			Units
V _{IH}	Minimum HIGH Level			2.0	2.0	2.0	V
	Input Voltage						
V _{IL}	Maximum LOW Level			0.8	0.8	0.8	V
	Input Voltage						
V _{OH}	Minimum HIGH Level	$V_{IN} = V_{IH}$ or V_{IL}					
	Output Voltage	$ I_{OUT} = 20 \mu A$	V_{CC}	V _{CC} - 0.1	V _{CC} - 0.1	V _{CC} - 0.1	V
		$ I_{OUT} = 4.0 \text{ mA}, V_{CC} = 4.5 \text{V}$	4.2	3.98	3.84	3.7	V
		$ I_{OUT} = 4.8 \text{ mA}, V_{CC} = 5.5 \text{V}$	5.2	4.98	4.84	4.7	V
V _{OL}	Maximum LOW Level	$V_{IN} = V_{IH}$					
	Voltage	$ I_{OUT} = 20 \mu A$	0	0.1	0.1	0.1	V
		$ I_{OUT} = 4.0 \text{ mA}, V_{CC} = 4.5 \text{V}$	0.2	0.26	0.33	0.4	V
		$ I_{OUT} = 4.8 \text{ mA}, V_{CC} = 5.5 \text{V}$	0.2	0.26	0.33	0.4	V
I _{IN}	Maximum Input	$V_{IN} = V_{CC}$ or GND, V_{IH} or V_{IL}		±0.1	±1.0	±1.0	μΑ
	Current						
Icc	Maximum Quiescent	$V_{IN} = V_{CC}$ or GND		2.0	20	40	μΑ
	Supply Current	$I_{OUT} = 0 \mu A$					
		V _{IN} = 2.4V or 0.5V (Note 4)		1.2	1.4	1.5	mA

Note 4: This is measured per input with all other inputs held at $V_{\mbox{CC}}$ or ground.

AC Electrical Characteristics

 $V_{CC} = 5.0V$, $t_r = t_f = 6$ ns, $C_L = 15$ pF, $T_A = 25$ °C

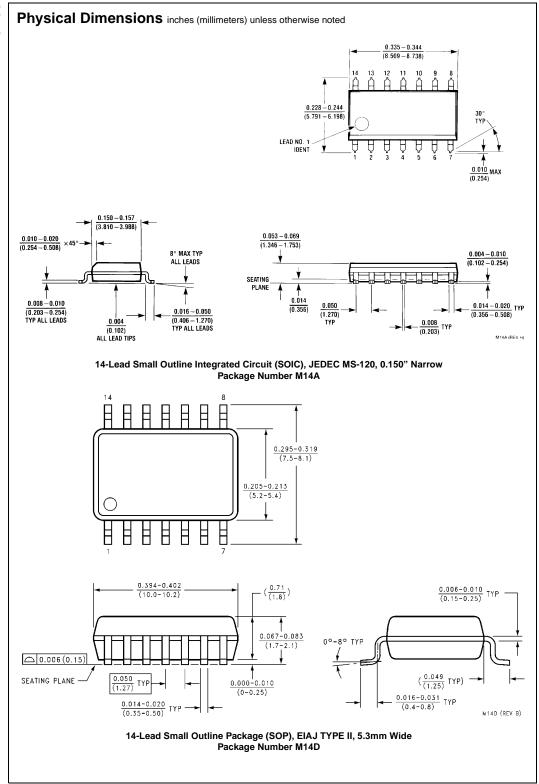
Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
t _{PLH} , t _{PHL}	Maximum Propagation Delay		9	15	ns

AC Electrical Characteristics

 $V_{CC} = 5.0V \pm 10\%, t_r = t_f = 6 \text{ ns, } C_L = 50 \text{ pF}$

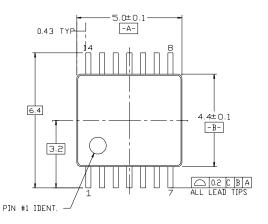
Symbol	ol Parameter	Conditions	T _A = 25°C		$T_A = -40 \text{ to } 85^{\circ}\text{C}$	T _A = -55 to 125°C	Units
Cynnbon			Тур		Guaranteed L	imits	Oilles
t _{PLH} , t _{PHL}	Maximum Propagation Delay		11	18	23	27	ns
t _{THL} , t _{TLH}	Maximum Output Rise & Fall Time		7	15	19	22	ns
C _{PD}	Power Dissipation Capacitance	(Note 5)	38				pF
C _{IN}	Input Capacitance		5	10	10	10	pF

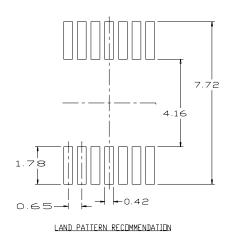
Note 5: C_{PD} determines the no load dynamic power consumption. $P_D = C_{PD} \ V_{CC} 2 \ f + I_{CC} \ V_{CC}$ and the no load dynamic current consumption, $I_S = C_{PD} \ V_{CC} 2 \ f + I_{CC} \ V_{CC}$ and the no load dynamic current consumption, $I_S = C_{PD} \ V_{CC} 2 \ f + I_{CC} \ V_{$

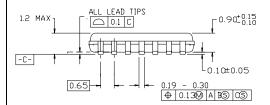


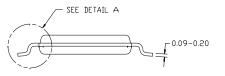
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

14LD, TSSOP, JEDEC MO-153, 4.4MM WIDE



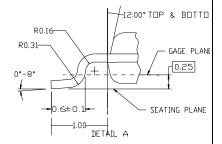






NOTES

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ABJREF NOTE 6, DATED 7/93
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS



14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 0.740 - 0.770 (18.80 - 19.56)0.090 (2.286) 14 13 12 11 10 9 8 14 13 12 INDEX AREA 0.250 ± 0.010 (6.350±0.254) PIN NO. 1 IDENT PIN NO. 1 IDENT 1 2 3 4 5 6 7 1 2 3 $\frac{0.092}{(2.337)}$ DIA $\frac{0.030}{(0.762)}$ MAX OPTION 1 OPTION 02 $\frac{0.135 \pm 0.005}{(3.429 \pm 0.127)}$ 0.300 - 0.320(7.620 - 8.128) 0.065 0.145 - 0.200 0.060 (1.524) 4° TYP Optional (1.651) (3.683 - 5.080)95°±5° $\frac{0.008 - 0.016}{(0.203 - 0.406)}$ TYP 0.020 (0.508)0.125 - 0.150 $\overline{(3.175 - 3.810)}$ $\overline{(1.905 \pm 0.381)}$ 0.014-0.023 TYP (7.112)-MIN $\frac{0.100 \pm 0.010}{(2.540 \pm 0.254)} \text{ TYP}$ (0.356 - 0.584) $\frac{0.050 \pm 0.010}{(1.270 - 0.254)} \text{ TYP}$ $0.325 ^{\,+\,0.040}_{\,-\,0.015}$

14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N14A

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8.255 + 1.016

N14A (REV.F)

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